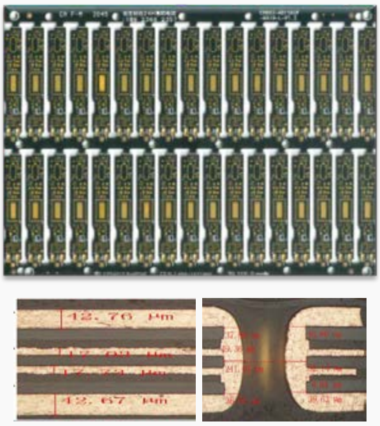
津日股份有限公司
NESSIE INDUSTRIAL CORP.

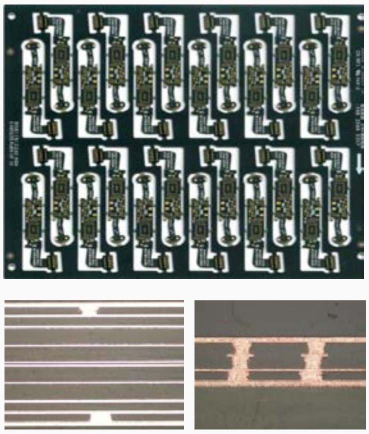
FPC 製程能力

項次	技術項目	階段	規格
1	Layers	MP	FPC：1-8L RFPC：2-10L
		RD	FPC：8-10L RFPC：10-16L
2	Size	MP	19.7”×31.5”（500mm×550mm）
		RD	19.7”×47.2”（500mm×620mm）
3	RFPC BVH Stacking	MP	1+N+1、1+1+N+1+1、2+N+2、3+N+3
		RD	Anylayer
4	Cu thickness	MP	1/3OZ-3OZ
		RD	1/4OZ-4OZ
5	Mechanical Min-drilling	MP	0.10mm/0.30mm
		RD	0.10mm/0.25mm
6	PTH Min-Cu thickness	MP	≥30um
		RD	≥35um
7	Plating Max. aspect ratio	MP	08:01
		RD	09:01
8	Laser Min-drilling	MP	0.075mm/0.225mm
		RD	0.075mm/0.2mm
9	Tolerance Hole	MP	±4.5/%%
		RD	±4/%%
10	Tolerance Impedance	MP	±9%
		RD	±8%

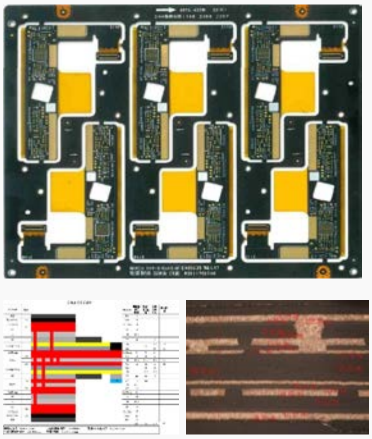
HDI產品展示



- 4-layer FPC HDI 1
- Laser drilling and hole filling process
- Line width and line spacing 0.075/0.075mm
- Immersion nickel gold



- 10-layer HDI 3 RFPC
- Laser drilling, 3-stage stacked hole process
- Line width and line spacing 0.05/0.05mm
- Immersion nickel gold



- 6 layers 1+2+2+1 Anylayer HDI RFPC
- Multiple laser drilling and hole filling processes
- Line width and line spacing 0.06/0.04mm
- CPK requirement is >1.33.

SMT 產品展示